

Preliminary Amendment

National Stage Entry of PCT/JP2003/013147

Attorney Docket No.: Q87201

AMENDMENTS TO THE SPECIFICATION

Amend the specification by adding before the first line the sentence:

This application is a National Stage of PCT application PCT/JP2003/013147 filed on October 14, 2003, claiming priority to Japanese Application No. 2002-302825 filed on October 17, 2002 and Japanese Application No. 2003-344180 filed October 2, 2003.

Please replace the paragraph on page 55 bridging pages 56 and 57 with the following amended paragraph:

The sealant of the present invention can be added with an epoxy resin, and the thus obtained sealant can be used as an elastic adhesive and the like. Examples of the epoxy resin include epichlorohydrin-bisphenol A-type epoxy resins, epichlorohydrin-bisphenol F-type epoxy resins, flame resistant epoxy resins such as glycidyl ether of tetrabromobisphenol A, novolac-type epoxy resins, hydrogenated bisphenol A-type epoxy resins, epoxy resins of the type of glycidyl ether of bisphenol A propyleneoxide adduct, p-oxybenzoic acid glycidyl ether ester-type epoxy resins, m-aminophenol based epoxy resins, diaminodiphenylmethane based epoxy resins, urethane modified epoxy resins, various alicyclic epoxy resins, N,N-diglycidylaniline, N,N-diglycidyl-o-toluidine, triglycidyl isocyanurate, polyalkylene glycol diglycidyl ether, glycidyl ethers of polyhydric alcohols such as glycerin, hydantoin-type epoxy resins and epoxidized substances of unsaturated polymers such as petroleum resins; however the epoxy resin is not limited to these examples, and commonly used epoxy resins can be used. Epoxy resins having at least two epoxy groups in one molecule are preferable because such compositions are high in reactivity when curing is made, and the cured substances can easily form three dimensional networks. Examples of further preferable epoxy resins include bisphenol A-type epoxy resins or

Preliminary Amendment

National Stage Entry of PCT/JP2003/013147

Attorney Docket No.: Q87201

novolac-type epoxy resins. The ratio of the used amount of each of these epoxy resins to the used amount of the reactive silicon group-containing polymer falls, in terms of weight ratio, in the range such that the polymer/epoxy resin = 100/1 to 1/100. When the ratio of the polymer/epoxy resin is less than 1/100, the effect of improving the impact resistance and the toughness of the cured substance of the epoxy resin becomes hardly obtainable, while when the ratio of the polymer/epoxy resin exceeds 100/1, the strength of the cured substance of the polymer becomes insufficient. The preferable ratio of the used amounts is varied depending on the application of the curable resin composition and hence cannot be unconditionally determined; for example, when the impact resistance, flexibility, toughness, and peel strength and the like of the cured substance of the epoxy resin are to be improved, it is recommended that in relation to 100 parts by weight of the epoxy resin, 1 to 100 parts by weight of the polymer, further preferably 5 to 100 parts by weight of the polymer is used. On the other hand, when the strength of the cured substance of the polymer is to be improved, it is recommended that in relation to 100 parts of the ~~(A)component+(B)component~~ the reactive silicon group-containing polymer, 1 to 200 parts by weight of the epoxy resin, further preferably 5 to 100 parts by weight of the epoxy resin is used.

Please replace the second full paragraph on page 67 with the following amended paragraph:

A polymer was obtained similarly to Synthesis Example 2 by using CuBr (3.67g, 25.6 mmol), acetonitrile (46 mL), diethyl 2,5-dibromoadipate (9.59g, 26.6 mmol), butyl acrylate (382 g, 2.96 mol), methyl acrylate (39 g, 0.44 mol), triamine (2.58 mL, 12.78 mmol) and 1,7-octadiene (53 mL, 0.43 mol).